



BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 2-801: Thermal conductivity test for base materials

National foreword

This British Standard is the UK implementation of EN IEC 61189-2-801:2023. It is identical to IEC 61189-2-801:2023. It supersedes BS IEC 61189-2-801:2023, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

Date	Text affected
31 December 2023	This corrigendum renumbers BS IEC 61189-2-801:2023 as BS EN IEC 61189-2-801:2023